



Product Change Notification

Change Notification #: 115839 - 00
Change Title: Intel® Server System R2208GZ4GC,
PCN 115839-00, Product Design, Label,
Update Regulatory and Safety Labels and
change air duct lock feature
Date of Publication: October 9, 2017

Key Characteristics of the Change:

Product Design, Label

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material: *	Oct 26, 2017
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* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is implementing the following changes on the Intel® Server System R2208GZ4GC:

1. Update the packaging regulatory label, by replacing the BSMI logo with the new version that includes RoHS text to the label, New Australia/New Zealand (RCM) logo, Safety Nemko logo and replace GOST logo with EAC logo for certification update. Please see Figure-1 and Figure-2 below for details.



Figure-1: Pre change label



Figure-2: Post change label

2. Update the system regulatory label, by replacing the BSMI logo with the new version that includes RoHS text to the label, New Australia/New Zealand (RCM) Logo and the Safety Nemko Logo. Please see Figure-3 and Figure-4 below for details.



Figure-3: Pre-Change



Figure-4: Post-Change

3. Update Motherboard to PBA G11481-356 with the below changes:
 - a. Update the PBA label using a small label with RCM logo to cover C-Tick logo. Please see Figure-1 and Figure-2 below for details.

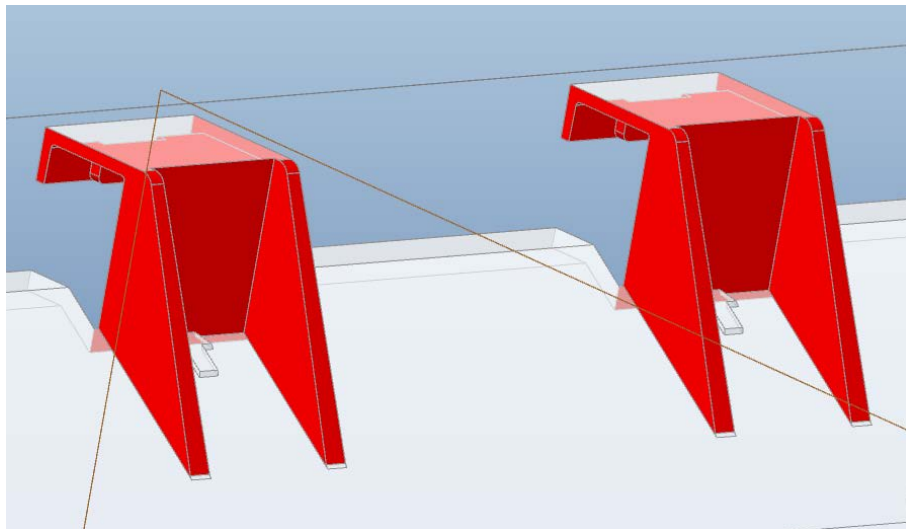


Figure-1: Pre-Change

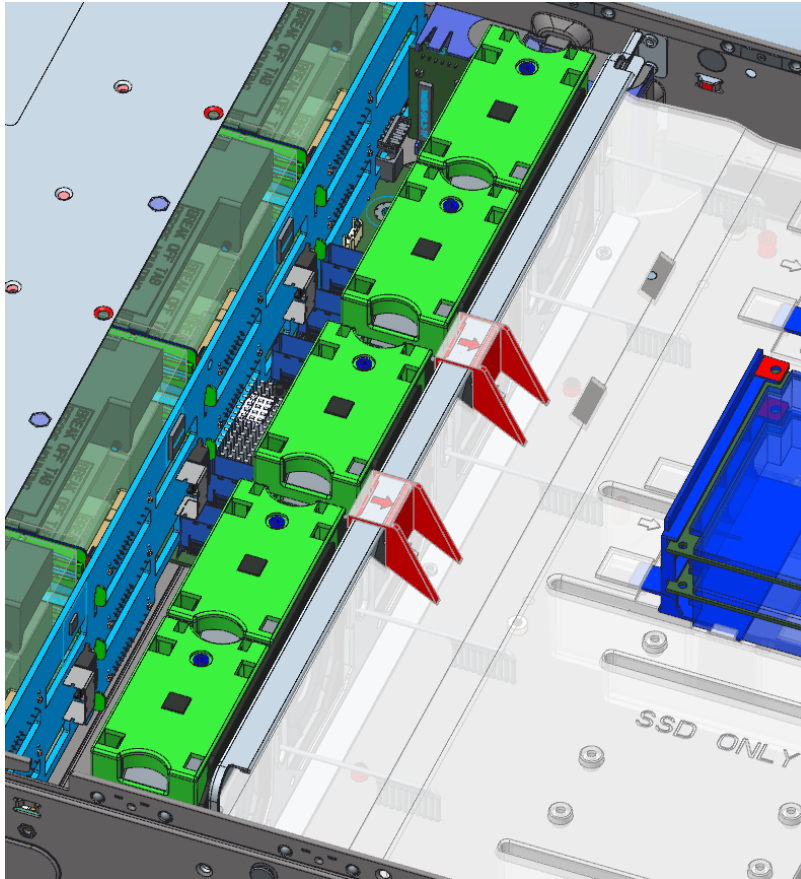


Figure-2: Post-Change

- b. Update CPLD to ensure system remains off after an over current event until the system has been AC power cycled.
4. Change air duct lock feature: Change air duct lock hook so the air duct will hook over the FAN bulkhead. This will improve the fixing of air duct during transportation.



New air duct lock hook



New air duct lock hook

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from those changes, but encourages customers to understand the changes and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
R2208GZ4GC	917001	G46831-006	G11481-355	G46831-007	G11481-356

PCN Revision History:

Date of Revision:
October 9, 2017

Revision Number:
00

Reason:
Originally Published PCN



Product Change Notification

115839 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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